

MECHANICAL CASE OUTLINE

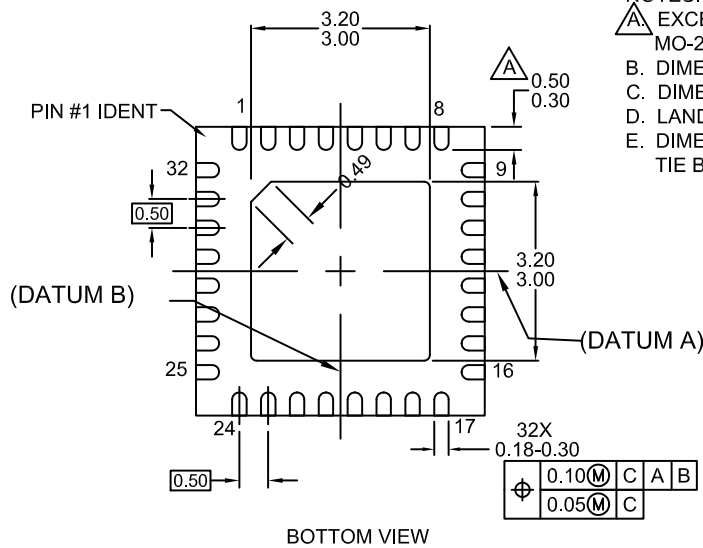
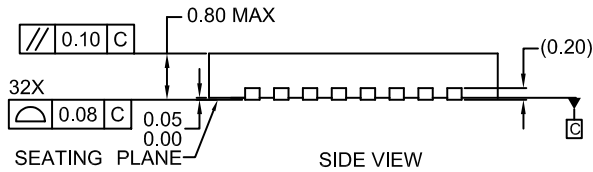
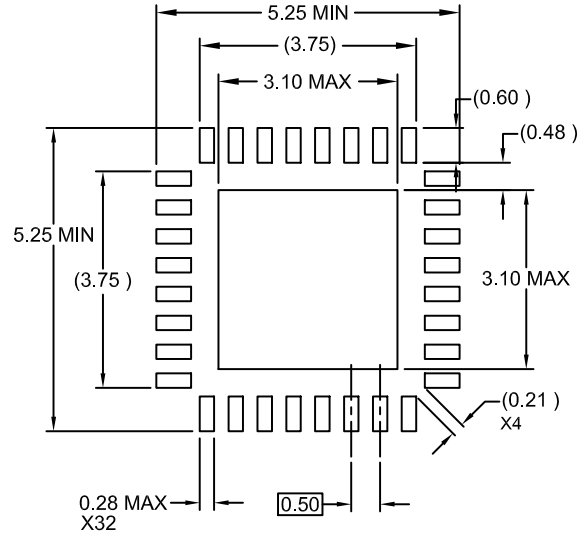
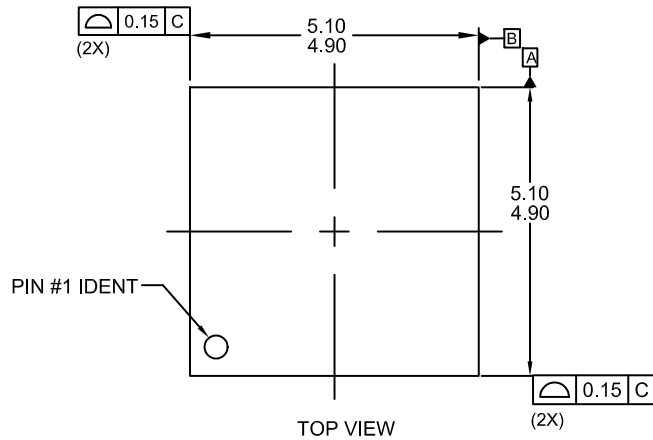
PACKAGE DIMENSIONS

ON Semiconductor®



WQFN32 5x5, 0.5P
CASE 510BV
ISSUE O

DATE 31 AUG 2016



- NOTES:
- A. EXCEPT WHERE NOTED, CONFORMS TO JEDEC REGISTRATION MO-220, VARIATION WHHD-6.
 - B. DIMENSIONS ARE IN MILLIMETERS.
 - C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
 - D. LAND PATTERN PER IPC SM-782.
 - E. DIMENSIONS ARE NOT INCLUSIVE OF BURRS, MOLD FLASH, OR TIE BAR PROTRUSIONS.

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